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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of: Smith et al.

Docket:

TI-22782B

Appl. No.:

09/757,073

Examiner:

E. Cameron

Filed:

1/8/01

Art Unit:

1762

For:

Polyol-Based Method For Forming Thin Film Aerogels On Semiconductor

Substrates

FACSIMILE CERTIFICATE

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X FACSIMILE COVER SHEET (I SHEET) NEW APPLICATION DECLARATION ASSIGNMENT FORMAL DRAWINGS INFORMAL DRAWINGS CONTINUATION APPN DIVISIONAL APPN		X AMENDMENT 111.1 (2 Pages) EOT (# Pages) NOTICE OF APPEAL (# Pages) X TERMINAL DISCLAIMER ISSUE FEE X PETITION TO ACCEPT UNINTENTIONALLY DELAYED CLAIM FOR PRIORITY
NAME OF INVENTOR(S):		RECEIPT DATE & SERIAL NO.:
Smith, et al.		Appl. No.: 09/757,073
TITLE OF INVENTION:		Filing Date: 1/08/01
Polyol-Based Method for Forming Thin Film Aerogels on Semiconductor Substrates		
TI FILE NO:	DEPOSIT ACCT. NO.:	
TI-22782B	20-0668	
FAXED: 6/21/04 DUE: 7/19/04		
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